

What is claimed is:

1. A solder for use in soldering to a surface coated with nickel by electroless plating with a phosphorus-containing plating solution, comprising 60 - 64 mass % of Sn, 0.002 - 0.01 mass % of P, 0.04 - 0.3 mass % of Cu, and a remainder of Pb.
2. A solder as claimed in claim 1 which is in the form of a solder ball, a solder paste, preformed solder, wire solder, or flux-cored wire solder.
3. A soldering method comprising soldering the solder claimed in claim 1 to a surface coated with nickel by electroless plating with a phosphorus-containing plating solution.
4. A soldered joint comprising the solder claimed in claim 1 formed on a surface coated with nickel by electroless plating with a phosphorus-containing plating solution.
5. A method of forming a solder bump comprising heating a solder ball comprising the solder claimed in claim 1 on a surface coated with nickel by electroless plating with a phosphorus-containing plating solution.
6. A solder bump comprising the solder claimed in claim 1 formed on a surface coated with nickel by electroless plating with a phosphorus-containing plating solution.
7. A substrate for a ball grid array package including a plurality of

solder bumps comprising the solder claimed in claim 1 disposed on Cu electrode pads coated with nickel by electroless plating with a phosphorus-containing plating solution.